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Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

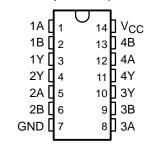
The 'HC266 are composed of four independent 2-input exclusive-NOR gates and feature open-drain outputs. They perform the Boolean function $Y = \overline{A} \otimes \overline{B}$ or $Y = \overline{AB} + \overline{AB}$ in positive logic.

The SN54HC266 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74HC266 is characterized for operation from –40°C to 85°C.

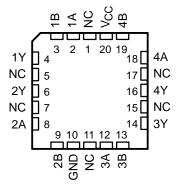
FUNCTION TABLE

INP	UTS	OUTPUT
Α	В	Y
L	L	Н
L	H L	L
Н	L	L
Н	Н	Н

SN54HC266 . . . J OR W PACKAGE SN74HC266 . . . D OR N PACKAGE (TOP VIEW)

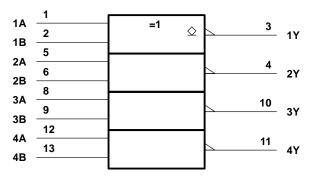


SN54HC266 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

logic diagram, each gate (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

SN54HC266, SN74HC266 QUADRUPLE 2-INPUT EXCLUSIVE-NOR GATES WITH OPEN-DRAIN OUTPUTS

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absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	127°C/W
N package	78°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

			SI	SN54HC266		SN74HC266			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
٧ıн	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		$V_{CC} = 6 V$	4.2		'n	4.2			
	Low-level input voltage	V _{CC} = 2 V	0	Ş	0.5	0		0.5	
VIL		V _{CC} = 4.5 V	0	9	1.35	0		1.35	V
		V _{CC} = 6 V	0	5	1.8	0		1.8	
٧ _I	Input voltage		0	20	VCC	0		VCC	V
Vo	Output voltage		0)	VCC	0		VCC	V
	Input transition (rise and fall) time	V _{CC} = 2 V	0		1000	0		1000	
t _t		V _{CC} = 4.5 V	0		500	0		500	ns
		V _{CC} = 6 V	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vaa	T _A = 25°C			SN54HC266		SN74HC266		UNIT				
PARAMETER	PARAMETER 1EST CO	DINDITIONS	vcc	MIN	TYP	MAX	MIN N	ΛΑΝ	MIN	MAX	UNIT				
IOH	$V_I = V_{IH} \text{ or } V_{IL}$	AO = ACC	6 V		0.01	0.5		10		5	μΑ				
		I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1					
V _{OL} V _I = V _{II}			4.5 V		0.001	0.1		0.1		0.1					
	V_{OL} $V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1	200	0.1		0.1	V				
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26	77	0.4		0.33					
							$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26	27/	0.4		0.33
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100	0 ±1	000	±1000		nA				
lcc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			2	Q	40		20	μΑ				
C _i			2 V to 6 V		3	10		10		10	pF				



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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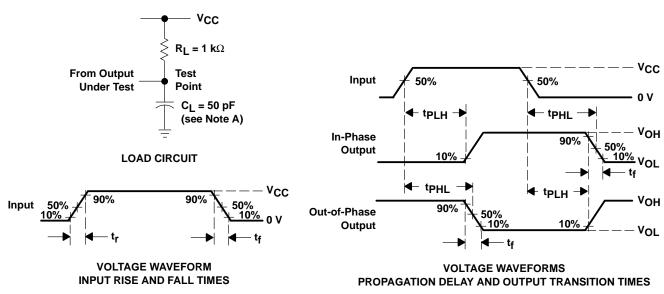
switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO		FROM	то	V	T,	Վ = 25° C	;	SN54F	IC266	SN74H	C266	UNIT						
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT								
	2 V		60	125		190		155											
t _{PLH}	A or B	Υ	4.5 V		13	25		38		31	ns								
											6 V		10	23		32		26	
		2 V		60	100		150		125										
t _{PHL}	A or B	Y	Y	4.5 V		13	20	'	30		25	ns							
	6 V		10	17	27/	25		21											
			2 V		28	75	70,	110		95									
t _t			Υ	Y	Υ	Υ	Υ	4.5 V		8	15	14	22		19	ns			
			6 V		6	13		19		16									

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	35	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_f = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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